Title (en)

METHOD AND DEVICE FOR TREATING SUBSTRATES

Title (de)

VORRICHTUNG UND VERFAHREN ZUM BEHANDELN VON SUBSTRATEN

Title (fr)

PROCEDE ET DISPOSITIF POUR TRAITER DES SUBSTRATS

Publication

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Application

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Abstract (en)

[origin: WO0049644A1] The aim of the invention is to increase the throughput capacity of a conventional substrate treatment device by essentially maintaining the floor space required. To this end, a device and a method for treating substrates in at least one of two basins is provided. Said basins can be filled with at least two treatment fluids. The method comprises the following steps: a) processing a first treatment fluid in a processing unit that is shared by the two basins, b) charging the basin with substrates, c) passing at least the second treatment fluid into the basin and e) removing the substrates from the basin, whereby the processing steps in the relevant basins are controlled at staggered intervals in such a way that a time period is provided between the end of step c) in one of the basins and the beginning of step c) in another basin, whereby said time period is sufficiently long for processing the first treatment fluid.

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